

Title (en)

METHOD FOR TRANSFERRING ELECTRONIC COMPONENTS

Title (de)

VERFAHREN ZUM TRANSFERIEREN VON ELEKTRONISCHEN BAUELEMENTEN

Title (fr)

PROCEDE DE TRANSFERT DES COMPOSANTS ELECTRONIQUES

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Application

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Abstract (en)

[origin: WO2007014880A1] The invention relates to a method for transferring electronic components (210), especially flip-chips or bare dies, from a sticky support film (204) onto a transfer head (250). The inventive method comprises the following steps: a) transferring the support film (204) to a vacuum pick-up device (220) which comprises a planar suction surface (223) which is provided with openings, a face of the support film (204) carrying the components (210) facing the suction surface, b) applying a reduced pressure to the vacuum pick-up device (220) so that the components (210) are sucked off by the suction surface, c) reducing the stickiness of the support film (204) so that the adhesive force exerted by the support film (204) on the components (210) is smaller than the suction force exerted by the vacuum pick-up device (220) on the components (210), d) removing the support film (204) from the vacuum pick-up device (220), the components (210) remaining on the vacuum pick-up device (220), and e) picking up the components (210) by means of a transfer head (250) which comprises at least one component holding device (252). The invention also relates a device for handling electronic components (210), especially for use as a vacuum pick-up device (220) for carrying out the inventive method.

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